

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method of making a heat-sensitive lithographic printing plate precursor comprising the steps of
 - (i) providing a web of a lithographic support having a hydrophilic surface;
 - (ii) applying a coating comprising a phenolic resin on the hydrophilic surface of the web;
 - (iii) drying the coating;
 - (iv) a heating step wherein the web temperature is maintained above 150°C during a period of between 1 and 30 seconds ~~the glass transition temperature of the phenolic resin T_g during a period of between 0.1 and 60 seconds~~;
 - (v) an active cooling step wherein the web temperature is reduced at an average cooling rate which is higher than if the web would be kept under ambient conditions and which is between 0.5°C/s 3°C/s and 30°C/s; and
 - (vi) winding the precursor on a core or cutting the precursor into sheets.
2. (Previously Presented) The method according to claim 1 wherein the average cooling rate is not higher than 20°C/s.
3. (Previously Presented) The method according to claim 1 wherein the average cooling rate is not higher than 10°C/s.
4. (Currently Amended) The method according to claim 1 wherein at the beginning of the cooling step the web temperature is higher than the glass transition temperature of the phenolic resin (T_g), [[T_g]] and wherein during the cooling step the web temperature is reduced from T₁ to T₂, T₁ being higher than T_g and T₂ being lower than T_g, at an average cooling rate which is lower than 10°C/s.
5. (Previously Presented) The method according to claim 4 wherein during the cooling step the web temperature is reduced
 - in a first phase down to T₁ at an average cooling rate of at least 10°C/s; and
 - in a second phase from T₁ to T₂ at an average cooling rate which is lower than 10°C/s.
6. (Previously Presented) The method according to claim 4 wherein during the cooling step the web temperature is reduced
 - in a first phase down to T₁ at an average cooling rate of at least 10°C/s;

- in a second phase from T1 to T2 at an average cooling rate which is lower than 10°C/s; and
- in a third phase from T2 to about ambient temperature at an average cooling rate of at least 10°C/s.

7. (Previously Presented) The method according to claim 4 wherein the cooling from T1 to T2 proceeds at an average cooling rate which is lower than 5°C/s.

8. (Previously Presented) The method according to claim 4 wherein T1 is Tg+20°C and T2 is Tg-20°C.

9. (Previously Presented) The method according to claim 4 wherein T1 is Tg+10°C and T2 is Tg-10°C.

10. (Currently Amended) The method according to claim 1 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

11. (Currently Amended) The method according to claim 2 wherein at the beginning of the cooling step the web temperature is higher than the glass transition temperature of the phenolic resin (Tg), [[Tg]] and wherein during the cooling step the web temperature is reduced from T1 to T2, T1 being higher than Tg and T2 being lower than Tg, at an average cooling rate which is lower than 10°C/s.

12. (Currently Amended) The method according to claim 3 wherein at the beginning of the cooling step the web temperature is higher than the glass transition temperature of the phenolic resin (Tg), [[Tg]] and wherein during the cooling step the web temperature is reduced from T1 to T2, T1 being higher than Tg and T2 being lower than Tg, at an average cooling rate which is lower than 10°C/s.

13. (Previously Presented) The method according to claim 11 wherein during the cooling step the web temperature is reduced

- in a first phase down to T1 at an average cooling rate of at least 10°C/s; and
- in a second phase from T1 to T2 at an average cooling rate which is lower than 10°C/s.

14. (Previously Presented) The method according to claim 12 wherein during the cooling step the web temperature is reduced

- in a first phase down to T1 at an average cooling rate of at least 10°C/s; and
- in a second phase from T1 to T2 at an average cooling rate which is lower than 10°C/s.

15. (Previously Presented) The method according to claim 11 wherein during the cooling step the web temperature is reduced

- in a first phase down to T1 at an average cooling rate of at least 10°C/s;
- in a second phase from T1 to T2 at an average cooling rate which is lower than 10°C/s; and
- in a third phase from T2 to about ambient temperature at an average cooling rate of at least 10°C/s.

16. (Previously Presented) The method according to claim 12 wherein during the cooling step the web temperature is reduced

- in a first phase down to T1 at an average cooling rate of at least 10°C/s;
- in a second phase from T1 to T2 at an average cooling rate which is lower than 10°C/s; and
- in a third phase from T2 to about ambient temperature at an average cooling rate of at least 10°C/s.

17. (Previously Presented) The method according to claim 5 wherein the cooling from T1 to T2 proceeds at an average cooling rate which is lower than 5°C/s.

18. (Previously Presented) The method according to claim 6 wherein the cooling from T1 to T2 proceeds at an average cooling rate which is lower than 5°C/s.

19. (Previously Presented) The method according to claim 5 wherein T1 is Tg+20°C and T2 is Tg-20°C.

20. (Previously Presented) The method according to claim 6 wherein T1 is Tg+20°C and T2 is Tg-20°C.

21. (Previously Presented) The method according to claim 7 wherein T1 is Tg+20°C and T2 is Tg-20°C.

22. (Previously Presented) The method according to claim 5 wherein T1 is Tg+10°C and T2 is Tg-10°C.

23. (Previously Presented) The method according to claim 6 wherein T1 is Tg+10°C and T2 is Tg-10°C.

24. (Previously Presented) The method according to claim 7 wherein T1 is Tg+10°C and T2 is Tg-10°C.

25. (Currently Amended) The method according to claim 2 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

26. (Currently Amended) The method according to claim 3 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

27. (Currently Amended) The method according to claim 4 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

28. (Currently Amended) The method according to claim 5 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

29. (Currently Amended) The method according to claim 6 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

30. (Currently Amended) The method according to claim 7 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

31. (Currently Amended) The method according to claim 8 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

32. (Currently Amended) The method according to claim 9 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

33. (Currently Amended) The method according to claim 11 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

34. (Currently Amended) The method according to claim 12 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

35. (Currently Amended) The method according to claim 14 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

36. (Currently Amended) The method according to claim 15 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

37. (Currently Amended) The method according to claim 16 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

38. (Currently Amended) The method according to claim 17 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

39. (Currently Amended) The method according to claim 18 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

40. (Currently Amended) The method according to claim 21 wherein the heating step is carried out by blowing hot air or steam onto the precursor or by exposing the precursor [[in]] to infrared or microwave radiation.

This listing of claims replaces all prior versions, and listings, of claims in the application.